

## IN THE CLAIMS

Please amend the following claims which are pending in the present application:

1. (Currently amended) A microelectronic assembly, comprising:  
at least a first die, having an integrated circuit formed therein;  
at least one functional contact on the die and connected to the integrated circuit;  
at least one redistribution conductor, including a pair of redistribution contacts on the same side of the die as the functional contact; and  
at least one pair of redistribution wirebonding wires, each redistribution wirebonding wire having a respective die portion, the die portions of the respective wirebonding wires being attached to the respective contacts of the redistribution conductor.
2. (Original) The microelectronic assembly of claim 1, further comprising:  
a plurality of redistribution conductors, each including a respective pair of contacts on the die; and  
a plurality of pairs of redistribution wirebonding wires, each redistribution wirebonding wire having a respective die portion, the die portions of the respective wirebonding wires being attached to the respective contacts of the redistribution conductors so as to connect a respective one of the pairs of

redistribution wirebonding wires through a respective redistribution conductor to one another.

3. (Original) The microelectronic assembly of claim 1, wherein the redistribution conductor includes a wirebonding wire between the contacts.
4. (Original) The microelectronic assembly of claim 1, further comprising:  
at least a first component other than the die;  
at least a first terminal on the first component, a first of the redistribution wires of the pair having a component portion attached to the terminal.
5. (Original) The microelectronic assembly of claim 4, further comprising:  
at least a second terminal on the first component, the other redistribution wire of the pair having a component portion attached to the terminal.
6. (Original) The microelectronic assembly of claim 4, wherein the component is a substrate to which the die is mounted and the terminal is outside an area of the die.
7. (Cancelled)

8. (Original) The microelectronic assembly of claim 4, further comprising:  
at least a third contact on the die, a second of the redistribution  
wirebonding wires of the pair having apportion attached to the third contact.
9. (Currently amended) A microelectronic assembly, comprising:  
a substrate;  
a microelectronic die having an integrated circuit formed therein, mounted  
to the substrate;  
a functional terminal on the substrate;  
a functional contact on the die and connected to the integrated circuit;  
a functional wirebonding wire connecting the functional terminal to the  
functional contact;  
a pair of redistribution terminals on the substrate; and  
a redistribution conductor interconnecting the redistribution terminals, the  
redistribution conductor including a redistribution contact on the same side of  
the die as the functional contact and a redistribution wirebonding wire having  
first and second portions attached to one of the redistribution terminals and to  
the redistribution contact, respectively.
10. (Original) The microelectronic assembly of claim 9, further comprising:  
a plurality of pairs of redistribution terminals on the substrate; and  
a plurality of redistribution conductors, each interconnecting the

redistribution terminals of a respective pair, each redistribution conductor including a redistribution contact on the die and a wirebonding wire having first and second portions attached to one of the redistribution terminals and to one of the redistribution contacts, respectively.

11. (Original) The microelectronic assembly of claim 9, wherein the redistribution conductor includes a pair of redistribution contacts on the die and a pair of redistribution wirebonding wires, each redistribution wirebonding wire having a respective first portion attached to a respective one of the redistribution terminals of the pair and a respective redistribution contact of the pair.

12. (Currently amended) A microelectronic assembly, comprising:

- a substrate;
- a microelectronic die, having an integrated circuit formed therein, mounted to the substrate;
- a plurality of functional terminals on the substrate;
- a plurality of functional contacts on the die, each being connected to the integrated circuit;
- a plurality of functional wirebonding wires, each having a first portion attached to a respective functional terminal and a second portion attached to a respective functional contact;
- a pair of redistribution terminals on the substrate; and

a redistribution conductor interconnecting the redistribution terminals, the redistribution conductor including a redistribution contact on the same side of the die as the functional contacts and a wirebonding wire having first and second portions attached to one of the redistribution terminals and to the redistribution contact, respectively.

13. (Original) The microelectronic assembly of claim 12, wherein the redistribution conductor is not connected to the integrated circuit between the redistribution contacts.

14. (Original) The microelectronic assembly of claim 12, wherein the redistribution conductor includes a pair of redistribution contacts on the die and a pair of redistribution wirebonding wires, each redistribution wirebonding wire having a respective first portion attached to a respective one of the redistribution terminals of the pair and a respective redistribution contact of the pair.

15.-18. (Cancelled)